

**NOTE: UNLESS OTHERWISE SPECIFIED**

1. LEAD CRIMP TO WIRE PART 1/2" OFF BOARD.
2. ADD JUMPER (ITEM 102 & 103), SECURE CENTER OF JUMPER TO PCB WITH "TAR-PAC" OR EQUIV.
3. LOG (ITEM 88) MUST NOT TOUCH ANY PART OF HEAT SINK (ITEM 86).
4. SECURE L1 AND L2 TOGETHER USING RTV.
5. BOND T4 TO PCB USING RTV.
6. DO NOT EXPOSE RTV TO WATER OR CLEANING FLUID FOR AT LEAST 24 HRS.
7. ADD JUMPER (ITEM 103) FROM PIN 3 OF Q1 TO PAD INDICATED BEFORE MOUNTING T2.
8. MOUNT CR8 AND CR11 ONTO PCB BY ADDING 5/16" OF SLEEVING (ITEM 118) ONTO THE CENTER LEG OF EACH PART.
9. THE ASBY KEY LEVEL MUST CORRESPOND WITH THE BILL OF MATERIAL KEY LEVEL. MANUFACTURING MUST STAMP THE LATEST KEY LEVEL IN THE APPROPRIATE LOCATION ON THE PCB AFTER ASSEMBLY OR REWORK.
10. ALL COMPONENTS TO BE HELD FLUSH AGAINST PCB SURFACE DURING SOLDERING UNLESS OTHERWISE SPECIFIED.
11. CLIP LEADS OF COMPONENTS C14, C15, C16, C17, C18 & C19 BEFORE HAVE SOLDERING. COMPONENTS SHOULD REST FLUSH TO BOARD.

12. SPACER (ITEM 111) TO BE TIE-WAPPED BETWEEN CAPS AND HEAT SINK PRIOR TO WAVE SOLDERING.
13. NO COMPONENT LOADED IN LOCATION C5.
14. ADD CR24, CR25 & CR26 (BENEATH R17 & R19) BY SOLDERING IN SERIES BETWEEN THE LEADS OF R17 & R19 AS SHOWN.
15. BOND CR25 TO PCB USING RTV.
16. BEND MIDDLE LEAD OF CR17, SOLDER R45 TO CR17 MIDDLE LEAD, INSERT OTHER LEAD OF R45 INTO CENTER PAD OF CR17 LAYOUT ON PCB AS SHOWN.
17. CORRECT JUMPER WIRE FROM CENTER POINT OF C13 AND C13 TO TOP LEAD OF R14. WIRE T25 TO AND SOLDER USED FOR JUMPER, WIRE ARROWED COMPONENT LEG ON CIRCUIT SIDE OF P.C.B.
18. APPLY RTV (ITEM 108) BETWEEN C7 AND CORE OR TRANSFORMER T2.

